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U.S. DEPARTMENT OF
Patent and T

FORM PTO-1596
1-31-92

DOCKET NO.: 4006-043



To the Honorable Commissioner of Patents

101077663

... attached original documents or copy thereof

JCS11 U.S. PTO
09/328580
06/10/99

1. Name of conveying party(ies):
Wen-Jyh SAH

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies):
Name: CHI MEI OPTOELECTRONICS CORP.
Internal Address: _____

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other _____
Execution Date: May 27, 1999

Street Address: Rm. 103, No. 47, Park Avenue-2Rd., Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.
City: _____ State/Country: _____ ZIP: _____
Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):
If the document is being filed together with a new application, the execution date of the application is: May 27, 1999
A. Patent Application No(s). _____

B. Patent No(s).
09/328580
Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: LOWE HAUPTMAN GOPSTEIN GILMAN & BERNER
Internal Address: _____
Street Address: 1700 Diagonal Road, Suite 310
City: Alexandria State: VA ZIP: 22314

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 3.41)..... \$40.00
 Enclosed
 Authorized to be charged to deposit account
8. Deposit account number:
07-1337

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9. Statement and signature.
To the best of my knowledge and belief the foregoing information is true and correct and any attached copy is a true copy of the original document.
Benjamin J. Hauptman, 29,310
Name and Registration No. of Person Signing

[Signature] Signature
6/10/99 Date
Total number of pages comprising cover sheet: 1

CMB No. 0851-0011 (exp. 4/94)

ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title) _____
A THIN FILM TRANSISTOR WITH A MULTI-METAL STRUCTURE A METHOD OF MANUFACTURING
THE SAME

The PATENT RIGHTS referred to in this agreement are:

(check one) a patent application for this invention, executed by the ASSIGNOR(S)
 concurrently with this assignment.

U.S. patent application Serial No. _____, filed _____

a U.S. patent application based on PCT International Application
 No. _____ filed on (date) _____ (U.S. patent application
 Serial No. _____, if known).

U.S. patent No. _____, issued _____.

The PATENT RIGHTS also include all divisions reissues, continuations and extensions of
 the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

(check one) U.S. patent rights only.

Worldwide patent rights. In this case, the assignee shall have the right to
 claim the benefit of the filing date of any U.S. or foreign patent application
 for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures
 appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) CHI MEI OPTOELECTRONICS CORP.

(Address) RM. 103, NO.: 47, PARK AVE-2RD., SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN,
R.O.C.

The ASSIGNEE is:

(check one) An individual.

A Partnership.

A Corporation of TAIWAN, R.O.C. (specify state or country)

(other) _____

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and
 valuable consideration, receipt of which is acknowledged, hereby assign(s) the following
 rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable
 provisions, based on any earlier patent applications for this invention.

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO

ASSIGNEE: CHI MEI OPTOELECTRONICS CORP.

INVENTION TITLE: A THIN FILM TRANSISTOR WITH A MULTI-METAL STRUCTURE

A METHOD OF MANUFACTURING THE SAME

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

<u>Wen-Jyh SAH</u>	<u>Sah Wen-Jyh</u>	<u>1999/5/27</u>
_____ Name of sole or first inventor	_____ Signature	_____ Date
_____ Name of second inventor, if any	_____ Signature	_____ Date
_____ Name of third inventor, if any	_____ Signature	_____ Date
_____ Name of fourth inventor, if any	_____ Signature	_____ Date
_____ Name of fifth inventor, if any	_____ Signature	_____ Date
_____ Name of sixth inventor, if any	_____ Signature	_____ Date
_____ Name of seventh inventor, if any	_____ Signature	_____ Date